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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/635,344	08/06/2003	Alan E. DeLaHoy	ENPI 0101 PUS	8089
22045	7590	01/06/2006	EXAMINER	
BROOKS KUSHMAN P.C. 1000 TOWN CENTER TWENTY-SECOND FLOOR SOUTHFIELD, MI 48075				MCDONALD, RODNEY GLENN
ART UNIT		PAPER NUMBER		
		1753		

DATE MAILED: 01/06/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No.	Applicant(s)
	10/635,344	DELAHOY ET AL.
	Examiner	Art Unit
	Rodney G. McDonald	1753

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) Responsive to communication(s) filed on 20 October 2005.  
 2a) This action is **FINAL**.                            2b) This action is non-final.  
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) Claim(s) 1-54 is/are pending in the application.  
 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.  
 5) Claim(s) \_\_\_\_\_ is/are allowed.  
 6) Claim(s) 1-54 is/are rejected.  
 7) Claim(s) \_\_\_\_\_ is/are objected to.  
 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) The specification is objected to by the Examiner.  
 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
 a) All    b) Some \* c) None of:  
 1. Certified copies of the priority documents have been received.  
 2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |   |   |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)                     |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                    | Paper No(s)/Mail Date. _____  |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____. | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
|   | 6) <input type="checkbox"/> Other: _____.                                   |

## DETAILED ACTION

### ***Allowable Subject Matter***

The indicated allowability of claims 16 and 44 are withdrawn in view of the newly discovered reference(s) to Kadokura et al. (U.S. Pat. 6,156,172). Rejections based on the newly cited reference(s) follow.

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1-9, 11-15, 18-26, 29-34, 36-43, 45, and 46 are rejected under 35 U.S.C. 103(a) as being unpatentable over Stollenwerk et al. (U.S. Pat. 6,150,030) (Stollenwerk) in view of Ando et al. (U.S. Pat. 6,458,253).

1. For claim 1, Applicant requires a method for sputter coating a substrate in a sputter coating reactor comprising providing a channel for gas to flow through wherein one or more portions of the channel surface includes at least one target material; flowing gas through the channel wherein at least a portion of the gas is non-laminarly flowing; and generating a plasma wherein the target material is sputtered off the channel surface to form a gaseous mixture containing target atoms that is transported to the substrate.
2. For claim 22, Applicant requires a method for depositing an oxide film on a substrate in a sputter coating reactor comprising providing a channel for a working gas

to flow through that has the channel defined by at least one target material; flowing the working gas through the channel non-laminarly; generating a plasma where a portion of the target is sputtered off the target material; and introducing a reactive gas comprising oxygen to form the oxide layer on the substrate.

3. For claim 36, Applicant requires a sputter coating system comprising at least one target material; an electrode having a channel-defining surface that contains at least one target material; and a source of non-laminarly flowing working gas.

4. Stollenwerk discloses a substrate coating apparatus (abstract) and a method for using it (col. 4, l. 24-26). The method comprising providing a channel (area between items **1a** and **1b** in Figure 1) between targets in which gas flows through (Figure 1). The gas flows in a turbulent fashion and a plasma is formed so that target material is sputtered to deposit on the substrate (col. 3, l. 28-47). The reactive gas can flow into the chamber after the targets (col. 4, l. 49-59) and react with the magnesium to form magnesium oxide.

5. For claim 2, Applicant requires the gas to be formed by turbulence. As noted above, the gas is turbulent (col. 3, l. 28-47).

6. For claim 3, Applicant requires the gas to be formed by flowing a first portion of a gas in a first direction and a second portion in a second direction that is non-parallel with the first direction. Stollenwerk discloses providing turbulent flowing gas from two separate sources that are flowing in non-parallel directions (Figure 1; items **7** and **11**).

7. For claims 4 and 37, Applicant requires the gas to be formed by flowing the gas through at least two orifices in non-parallel directions. As can be seen from Figure 1, the gas is formed from more than 2 sources that emit the gas in non-parallel fashion.

8. For claims 5 and 38, Applicant requires the gas to flow through a series of orifices. Figure 1 shows the limitation.

9. For claim 6, Applicant requires the Reynolds number of the turbulence to be at least 2000. Because the gas flow is “turbulent”, the Reynolds number is inherently greater than 2000. Applicant has specifically stated that “Typically, turbulent flow is characterized as having a Reynolds number greater than 2000.” (See specification at page 7, lines 23-24).

10. For claims 7 and 39, Applicant requires the channel surface to be part of a cathode. The targets are biased and therefore act as cathodes (col. 4, l. 41-44).

11. For claims 8 and 40, Applicant requires the channel to have a rectangular cross section. Figure 1 is in cross section and shows the channel to be rectangular.

12. For claim 9, Applicant requires the power to the target to be DC. Stollenwerk discloses the limitation (col. 4, l. 41-44).

13. For claims 11 and 24, Applicant requires the target to be metal or metal alloy. For claims 12 and 25, Applicant notes that the target can be magnesium. Stollenwerk discloses the target to be magnesium (col. 3, l. 31-32).

14. For claims 13, 31, 32, and 41, Applicant requires the target to be a first target material and a second target material opposite the first target material. Figure 1 shows the targets opposite each other.

15. For claims 14, 33, and 42, Applicant requires the first and second target material to comprise a metal or metal alloy. For claims 15, 34, and 43, Applicant notes that the target can be magnesium. Stollenwerk discloses the targets to be magnesium (col. 3, l. 31-32).

16. For claims 18 and 44, Applicant requires introducing a reactive gas into the chamber. Stollenwerk introduces oxygen or hydrogen (col. 4, l. 57-59).

17. For claims 19, 23, and 45, Applicant requires the reactive gas to be introduced at a position outside the channel. The reactive gas is introduced at a location so that the gas does not directly flow between the targets (col. 4, l. 51-53).

18. For claims 20 and 29, Applicant requires the reactive gas to be oxygen. For claim 21, the reactive gas is molecular hydrogen or molecular oxygen. For claim 30, the reactive gas can be molecular oxygen. When the hydrogen or oxygen reacts, the oxygen or hydrogen is converted to molecular state and thus is an active gas.

19. For claim 26, Applicant requires the oxide film to be magnesium oxide. Stollenwerk forms magnesium oxide (abstract).

20. The difference between Stollenwerk and the present claims is that locating the nozzle within the channel is not discussed.

21. Ando et al. teach locating a working gas nozzle at the end of the target channel but still located within the target channel. The working gas nozzle is made up of the anode 41 through which the working gas is introduced from the feed source 30.

(Column 5 lines 31-36; Column 6 lines 21-29; Column 6 lines 50-59; Figs. 1 and 7)

22. The motivation for introducing the sputtering gas within the channel but located at an end of the channel is that it allows for preventing reactive gas from entering the channel to contaminate the target surface. (Column 9 lines 29-38)
23. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified Stollenwerk et al. by locating the working gas nozzle within the channel but yet at an end location within the channel as taught by Ando et al. because it allows for preventing reactive gas from entering the channel to contaminate the target surface.
24. Claim 10 is rejected under 35 U.S.C. 103(a) as being unpatentable over Stollenwerk et al. in view of Ando et al. and further in view of US 5,810,982 to Sellers.
25. For claim 10, Applicant requires the power supply to the target to be pulsed DC power that is asymmetric bipolar.
26. Stollenwerk is described above, but does not disclose the power to be asymmetric bipolar.
27. Sellers discloses using asymmetric bipolar pulsed DC power for sputtering to prevent arcing that occurs when insulating films are sputtered (col. 4, l. 23-32).
28. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modified Stollenwerk in view of Ando et al. by utilizing asymmetric bipolar pulsed DC bias sputtering as taught by Sellers because of the desire to prevent arcing.

29. Claim 17 is rejected under 35 U.S.C. 103(a) as being unpatentable over Stollenwerk et al. in view of Ando et al. and further in view of ***Thin Film Processes*** by Vossen et al. (Vossen).

30. For claim 17, Applicant requires the target to comprise an electrically insulating block and a second electrically insulating block opposite the first block.

31. Stollenwerk is described above, but does not disclose the target to be an electrically insulating block. Stollenwerk does, however, teach reactive sputter deposit from a metal target.

32. Vossen discloses that reactive sputtering can be two art recognized equivalent methods. The first involves depositing from a metal target in a reactive gas atmosphere. The second involves depositing from a sputtering target of the same composition as the desired deposited layer in a reactive gas atmosphere. The only difference between the two reactive sputtering methods is the sputtering rate (pg. 48-49).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Stollenwerk in view of Ando et al. by utilizing reactive sputtering from an insulating MgO target as taught by Vossen because of the knowledge that the method would be an art recognized equivalent.

33. Claims 16 and 44 are rejected under 35 U.S.C. 103(a) as being unpatentable over Stollenwerk et al. in view of Ando et al. and further in view of Kadokura (U.S. Pat. 6,156,172).

34. For claims 16 and 44, Applicant's require four targets. The target materials can be the same.
35. Stollenwerk already establishes facing targets and target materials being the same i.e. magnesium. (See Stollenwerk discussed above)
36. Kadokura teaches that four targets can be used in order to form layers. Pairs of targets can face each other in a box type fashion. (See Fig. 5; Column 10 lines 10-17)
37. The motivation for utilizing a four targets is that it allows for preventing degradation in the thin film. (Column 4 lines 1-2)
38. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Stollenwerk in view of Ando et al. by utilizing four targets as taught by Kadokura because it allows for preventing degradation in the thin film.
39. Claims 1-9, 11-15, 18-43, and 47-54 rejected under 35 U.S.C. 103(a) as being unpatentable over US 5,889,295 to Rennie et al. (Rennie) in view of US 6,150,030 to Stollenwerk et al. (Stollenwerk) and US 6,458,253 Ando et al. (Ando et al.)
40. Claims 1-9, 11-15, 18-26, 29-34, 36-43, 45, and 46 are described above. For claim 27, Applicant requires the at least one target to comprise zinc and the oxide to comprise zinc oxide. For claim 28, the target comprises aluminum. For claim 35, the oxide film is aluminum-doped zinc oxide.
41. For claim 47, Applicant requires a method for depositing a nitride film comprising providing a channel for a working gas to flow through that has the channel defined by at least one target material; flowing the working gas through the channel non-laminarly; generating a plasma where a portion of the target is sputtered off the target material;

and introducing a reactive gas comprising nitrogen to form the oxide layer on the substrate. For claim 48, Applicant requires the reactive gas to be combined with the working gas while it is flowed through the channel. For claim 49, Applicant requires the reactive gas to be introduced at a position outside the channel. For claim 50, Applicant requires the target to comprise a metal or alloy or semiconductor. For claim 51, the metal can be aluminum or zinc. For claim 52, the nitride can be aluminum nitride. For claim 53, the target includes first and second target material. For claim 54, the target material is opposite each other.

42. Rennie discloses a method of manufacturing a semiconductor device (abstract) comprising forming a layer such as Al-doped ZnO or AlN by sputtering (col. 4, l. 32-55). The specifics of the sputtering process and apparatus are not described. It is inherent that if aluminum is deposited, as either a doping effect or as AlN, then aluminum is present in the sputtering target. Likewise, if ZnO is formed, then the target inherently contains zinc.

43. Stollenwerk discloses a sputtering apparatus and process comprising providing turbulent flowing gas. The benefit of using the method and apparatus of Stollenwerk is larger area substrates can be processed (col. 1, l. 1-67).

44. Ando et al. discloses a sputtering apparatus where the working gas nozzle is located within the channel but yet at an end location within the channel because it allows for preventing reactive gas from entering the channel to contaminate the target surface. (Column 5 lines 31-36; Column 6 lines 21-29; Column 6 lines 50-59; Figs. 1 and 7; Column 9 lines 29-38)

45. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the invention of Rennie to utilize the process and apparatus of Stollenwerk and to have located the nozzle within the channel but yet at an end location within the channel because of the desire to coat large area semiconductor substrates to produce numerous semiconductor chips.

46. Claim 10 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 5,889,295 to Rennie et al. (Rennie) in view of US 6,150,030 to Stollenwerk et al. (Stollenwerk) and US 6,458,253 Ando et al. (Ando et al.) as applied to claim 1 above, and further in view of US 5,810,982 to Sellers.

47. Claim 10 is described above. Rennie, Stollenwerk, Ando et al. and Sellers are described.

48. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the invention of Rennie in view of Stollenwerk and Ando et al. by utilizing asymmetric bipolar pulsed DC bias sputtering as taught by Sellers because of the desire to prevent arcing.

49. Claim 17 is rejected under 35 U.S.C. 103(a) as being unpatentable over US 5,889,295 to Rennie et al. (Rennie) in view of US 6,150,030 to Stollenwerk et al. (Stollenwerk) and US 6,458,253 Ando et al. (Ando et al.) as applied to claims 1, 13 above, and further in view of ***Thin Film Processes*** by Vossen et al. (Vossen).

50. Claim 17 is described above. Rennie, Stollenwerk, Ando et al. and Vossen are described above.

51. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the invention of Rennie in view of Stollenwerk and Ando et al. by utilizing reactive sputtering from an insulating ZnO target as taught by Vossen because of the knowledge that the method would be an art recognized equivalent.

52. Claims 16 and 44 are rejected under 35 U.S.C. 103(a) as being unpatentable over US 5,889,295 to Rennie et al. (Rennie) in view of US 6,150,030 to Stollenwerk et al. (Stollenwerk) and US 6,458,253 Ando et al. (Ando et al.) as applied to claims 1, 13, 36, 41 above, and further in view of Kadokura (U.S. Pat. 6,156,172).

53. For claims 16 and 44, Applicant's require four targets. The target materials can be the same.

54. Stollenwerk already establishes facing targets and target materials being the same i.e. magnesium. (See Stollenwerk discussed above)

55. Kadokura teaches that four targets can be used in order to form layers. Pairs of targets can face each other in a box type fashion. (See Fig. 5; Column 10 lines 10-17)

56. The motivation for utilizing a four targets is that it allows for preventing degradation in the thin film. (Column 4 lines 1-2)

57. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Rennie in view of Stollenwerk and Ando et al. by utilizing four targets as taught by Kadokura because it allows for preventing degradation in the thin film.

***Response to Arguments***

Applicant's arguments filed October 20, 2005 have been fully considered but they are not persuasive.

At the outset the Drawing objections, Specification objections and Claim objections have been overcome.

The 35 U.S.C. 102 (b) rejection has been overcome.

***RESPONSE TO THE ARGUMENTS OF THE 35 U.S.C. 103 REJECTIONS:***

Applicant has argued that Stollenwerk teach away from forming turbulence when the nozzle is positioned within the target channel. The Examiner has cited Ando et al. to rebut Applicant's position. Particularly Stollenwerk teaches locating the gas inlet at an end of the target to create turbulences. Ando et al. now of record suggests locating a gas inlet at the end of a target channel but yet still located within the target channel. The motivation for locating the gas inlet at this location is that it prevents the target from being contaminated from reactive gases. Therefore one of ordinary skill in the art would be motivated to modify Stollenwerk's apparatus in accordance with the teachings of Ando et al. because it prevents the target from being contaminated from reactive gases. Also it should be noted that Ando et al. teach as Column 6 lines 50-58 that the gas inlet structure, which is the anode, be a porous material and that such a porous material would cause the flow to be nondirectional and therefore turbulent. Furthermore, any gas arising from a nozzle in a sputtering after a particular distance would take on a turbulent flow due to the eddying and swirling from its regular path thus causing sputtering.

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This action will be made NON-Final because of the new references cited against the previously indicated allowable subject matter.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Rodney G. McDonald whose telephone number is 571-272-1340. The examiner can normally be reached on M- Th with Every other Friday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nam X. Nguyen can be reached on 571-272-1342. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Rodney G. McDonald  
Primary Examiner  
Art Unit 1753

RM  
January 4, 2006